

A10030566-1

Claims Presented

1. (Original) A laser submount, comprising:
a substrate;
a lens above the substrate; and
a laser above the substrate.
2. (Original) The laser submount of claim 1, wherein the substrate is selected from the group consisting of silicon, quartz, sodium borosilicate glass, sapphire, gallium arsenide, silicon carbide, and gallium phosphide.
3. (Currently Amended) The laser submount of claim 1, further comprising:
a [planaraization]] planarization layer covering the lens; and
an interconnect layer above the planarization layer.
4. (Original) The laser submount of claim 3, wherein the planarization layer is an oxide layer.
5. (Original) The laser submount of claim 3, further comprising:
a dielectric layer above the interconnect layer; and
a contact pad above the dielectric layer, wherein the laser is electrically connected to the contact pad.
6. (Original) The laser submount of claim 5, further comprising:
a sealing ring above the dielectric layer and surrounding the contact pad and the laser.
7. (Original) The laser submount of claim 1, further comprising:
at least one of a passive integrated circuit and an active integrated circuit.
- 8 - 14. (Cancelled)